RG3A THRU RG3M

GLASS PASSIVATED FAST SWITCHING RECTIFIER

Reverse Voltage - 50 to 1000 Volts Forward Current - 3.0 Amperes

FEATURES

- High temperature metallurgically bonded construction
 Glass passivated cavity-free junction
 Hermetically sealed package
 - ♦ 3.0 Ampere operation at T_A=55°C with no thermal runaway
 - Typical I_R less than 0.1µA
 - Capable of meeting environmental standards of MIL-S-19500
 - Fast switching for high efficiency
 - High temperature soldering guaranteed: 350°C/10 seconds, 0.375" (9.5mm) lead length, 5 lbs. (2.3kg) tension

MECHANICAL DATA

Case:Solid glass body Terminals: Solder plated axial leads, solderable per MIL-STD-750, Method 2026 Polarity: Color band denotes cathode end Mounting Position: Any Weight: 0.04 ounce, 1.1 grams

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

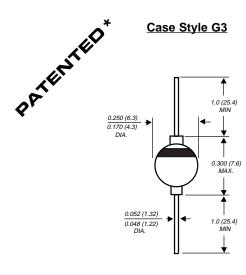
Ratings at 25°C ambient temperature unless otherwise specified.									
	SYMBOLS	RG3A	RG3B	RG3D	RG3G	RG3J	RG3K	RG3M	UNITS
Maximum repetitive peak reverse voltage	Vrrm	50	100	220	400	600	800	1000	Volts
Maximum RMS voltage	VRMS	35	70	140	280	420	560	700	Volts
Maximum DC blocking voltage	VDC	50	100	200	400	600	800	1000	Volts
Maximum average forward rectified current 0.375" (9.5mm) lead length at T _A =55°C	l(AV)				3.0				Amps
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	IFSM	100.0							Amps
Maximum instantaneous forward voltage at 3.0A	VF	1.3							Volts
Maximum average reverse currentTA=25°Cat rated peak reverse voltageTA=100°C	IR(AV)	2.0 100.0							μΑ
Maximum DC reverse current at rated DC blocking voltage	IR	5.0							μΑ
Maximum reverse recovery time (NOTE 1)	trr		150			250	400	500	ns
Typical junction capacitance (NOTE 2)	CJ	40.0						pF	
Typical thermal resistance (NOTE 3)	Rθja	22.0							°C/W
Operating junction and storage temperature range	TJ, TSTG	-65 to +175							°C

NOTES:

(2) Measured at 1.0 MHz and applied reverse voltage of 4.0 Volts

(3) Thermal resistance from junction to ambient at 0.375" (9.5mm) lead length, with both leads attached to heat sink



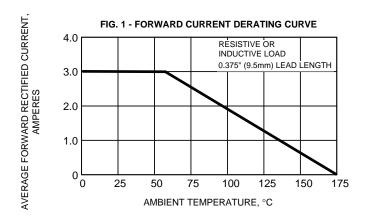


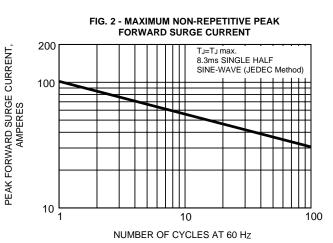
Dimensions in inches and (millimeters)

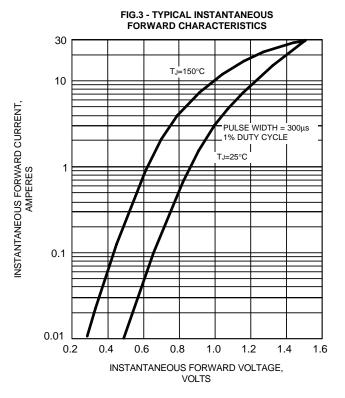
* Brazed-lead assembly is covered by Patent No. 3,930,306

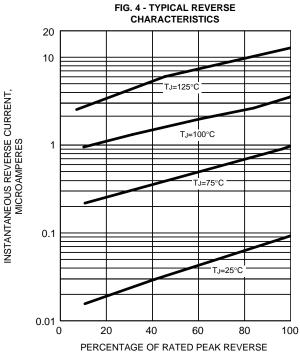
⁽¹⁾ Reverse recovery test conditions: IF=0.5A, IR=1.0A, Ir=0.25A

RATINGS AND CHARACTERISTIC CURVES RG3A AND RG3M

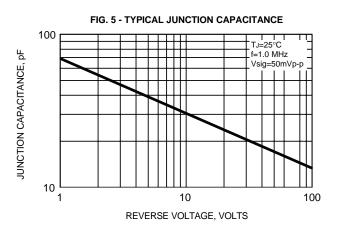












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